

LISTING OF THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the application:

1. (Previously presented) A process for producing a coated substrate having at least one metallic surface, comprising:

depositing an evaporation-coating glass in structured form at least on the at least one metallic surface.

2. (Previously presented) The process as claimed in claim 1, wherein the evaporation-coating glass is deposited by electron beam evaporation.

3. (Previously presented) A process for producing a coated substrate having a metallic surface, comprising:

producing at least one negatively structured first coating on the metallic surface;

depositing an hermetic evaporation-coating glass layer on the first coating; and

at least partially removing the at least one negatively structured first coating and the hermetic evaporation-coating glass layer thereon.

4. (Previously presented) The process as claimed in claim 3, wherein the step of producing the at least one negatively structured first coating on the metallic surface comprises the step of uncovering regions of the metallic surface that are to be coated.

5. (Previously presented) The process as claimed in claim 3, wherein the step of producing the at least one negatively structured first coating comprises the step of resist-coating or printing.

6. (Previously presented) The process as claimed in claim 3, wherein the step of at least partially removing the at least one negatively structured first coating comprises the step of lifting off regions of the hermetic evaporation-coating glass layer.

7. (Previously presented) The process as claimed in claim 3, wherein the hermetic evaporation-coating glass layer is deposited with a thickness that is less than the thickness of the at least one negatively structured first coating.

8. (Previously presented) The process as claimed in claim 3, further comprising the step of at least partially uncovering the at least one negatively structured first coating.

9. (Previously presented) The process as claimed in claim 8, wherein the step of at least partially uncovering the at least one negatively structured first coating comprises the step of planarizing the metallic surface having the at least one negatively structured first coating and the hermetic evaporation-coating glass layer thereon.

10. (Previously presented) The process as claimed in claim 8, wherein the step of partially uncovering the at least one negatively structured first coating comprises the step of mechanically removing material by a process selected from the group consisting of grinding, lapping, and polishing.

11. (Previously presented) The process as claimed in claim 3, wherein depositing the hermetic evaporation-coating glass layer comprises evaporation coating through a mask.

12. (Previously presented) The process as claimed in claim 3, further comprising depositing at least two hermetic evaporation-coating glass layers on the metallic substrate.

13. (Previously presented) The process as claimed in claim 12, wherein the at least two evaporation-coating glass layers comprise different compositions.

14. (Previously presented) The process as claimed in claim 3, wherein the hermetic evaporation-coating glass layer is deposited with a thickness in a range from 0.01 μm to 1 mm.

15. (Previously presented) The process as claimed in claim 3, wherein the hermetic evaporation-coating glass layer has a composition that is varied while being deposited.

16. (Previously presented) The process as claimed in claim 3, wherein depositing the hermetic evaporation-coating glass layer comprises co-evaporating evaporation-coating material from at least two sources.

17. (Previously presented) The process as claimed in claim 3, further comprising heating the metallic substrate during deposition of the hermetic evaporation-coating glass layer.

18. (Previously presented) The process as claimed in claim 3, wherein depositing the hermetic evaporation-coating glass layer occurs at a pressure that is at most 10^{-4} mbar.

19. (Previously presented) The process as claimed in claim 3, further comprising structuring the hermetic evaporation-coating glass layer following the depositing operation.

20. (Previously presented) The process as claimed in claim 19, wherein structuring the hermetic evaporation-coating glass layer comprises local etching.

21. (Previously presented) The process as claimed in claim 3, further comprising moving the metallic substrate with respect to a coating source during the depositing step.

22. (Previously presented) The process as claimed in claim 3, wherein depositing the hermetic evaporation-coating glass layer comprises plasma ion assisted deposition (PIAD).

23 through 32. (Cancelled)

33. (New) A process for producing a coated substrate, comprising:

depositing an evaporation-coating glass in structured form on a metallic surface of a solid metal substrate.

34. (New) A process for producing a coated substrate, comprising:

producing a negatively structured first coating on a metallic surface of a solid metal substrate;

depositing an hermetic evaporation-coating glass layer on the negatively structured first coating; and

at least partially removing the negatively structured first coating and the hermetic evaporation-coating glass layer thereon.

35. (New) The process as claimed in claim 34, wherein the step of producing the negatively structured first coating on the metallic surface comprises the step of uncovering regions of the metallic surface that are to be coated with the hermetic evaporation-coating glass layer.

36. (New) The process as claimed in claim 34, wherein the step of at least partially removing the negatively structured first coating comprises the step of lifting off regions of the hermetic evaporation-coating glass layer.

37. (New) The process as claimed in claim 34, wherein the hermetic evaporation-coating glass layer is deposited with a thickness that is less than the thickness of the negatively structured first coating.